THICK FILM (WIDE TERMINAL TYPE LOW RESISTANCE)

WU73 Wide Terminal Type Low Resistance Flat Chip Resistors (Low T.C.R.)



Coating color : Black

Features

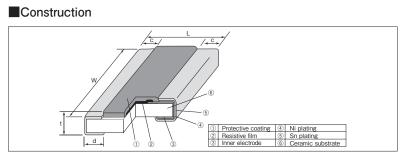
- Flat chip resistors of wide terminal type.
- High reliability and performance with T.C.R.
- $\pm 75 \times 10^{-6}$ /K \sim , resistance tolerance ± 1 %.
- Suitable for flow and reflow solderings.
- Products meet EU-RoHS requirements.
- AEC-Q200 Tested.

Applications

• Power supply, ECU etc.

Reference Standards

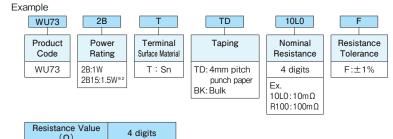
IEC 60115-8 JIS C 5201-8 EIAJ RC-2134C



Dimensions

Type (Inch Size Code)		Weight(g)				
	L±0.15	$W^{+0.1}_{-0.3}$	c±0.2	d±0.15	t±0.1	(1000pcs)
2B(0612)	1.6	3.2	0.4	0.45	0.6	12.0
2B15(0612)	1.6	3.2	0.4	0.45	0.6	12.0

Type Designation



(Ω)	4 digits		
10m~91m	10L0~91L0		
0.1	R100		

Contact us when you have control request for environmental hazardous material other than the substance specified by ${\rm EU}\mbox{-}{\rm RoHS}.$

For further information on taping, please refer to APPENDIX C on the back pages

Ratings

Type Power Rating	Rated Ambient Temp.	Rated Terminal Part Temp.	T.C.R. (×10 ⁻⁶ /K)	Resistance Range (Ω)	Resistance Tolerance	Operating Temp. Range	Taping & Q'ty/Reel (pcs)
				E24 & 25m, 50m ^{≋1}			
WU73 2B 1 W		115°C	±100	10m~12m	F:±1%	−55°C~155°C	5,000
	70℃		±75	13m~27m			
			±100	30m~100m			
WU73 2B15 1.5W ^{®2}	70°C	95℃	±100	10m~12m			
			±75	13m~27m			
			±100	30m~100m			

Rated voltage= $\sqrt{Power Rating \times Resistance value}$

 $\%1~25\mathrm{m}\,\Omega$ and $50\mathrm{m}\,\Omega$ are available.

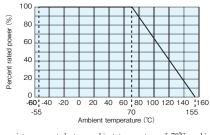
#2 If you use at the rated power, please keep the condition that the terminal of the resistor is below the rated terminal part temperature. Please refer to the derating curves based on the terminal temperature of right side on the next page.

If any questions arise whether to use the "Rated Ambient Temperature" or the "Rated Terminal Part Temperature" in your usage conditions, please give priority to the "Rated Terminal Part Temperature". For more details, please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog.



Derating Curve

Ambient temperature



For resistors operated at an ambient temperature of 70°C or higher, the power shall be derated in accordance with the derating curve.

Terminal part temperature

100

90 80

70 60

50

40

30

20

10

0 -60' -40

55

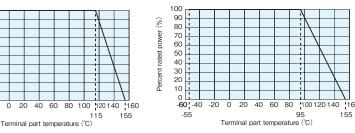
-20

20

0

Percent rated power (%)

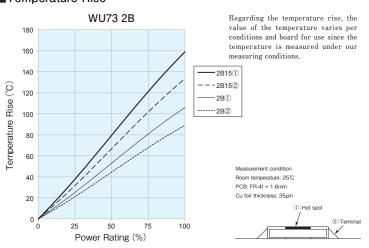
Terminal part temperature WU73 2B15(1.5W)



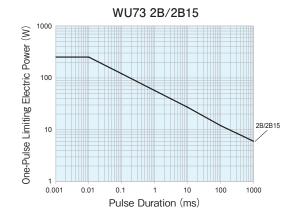
When the terminal part temperature of the resistor exceeds the rated terminal part temperature shown above, the power shall be derated according to the derating curve.

*Please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog before use

Temperature Rise



One-Pulse Limiting Electric Power



Please ask us about the resistance characteristic of continuous applied pulse. The pulse endurance values are not assured values, so be sure to check the products on actual equipment when you use them.

Performance

Test Items	Performance Requirements $\Delta R \pm (\% + 0.005 \Omega)$		Test Methods	
	Limit Typical			
Resistance	Within specified tolerance	—	25°C	
T.C.R.	Within specified T.C.R	—	+25℃/-55℃ and +25℃/+125℃	
Overload (Short time)	2	0.2	Rated voltage×2 for 5s	
Resistance to soldering heat	1	0.2	260°C±5°C, 10s±1s	
Bending test	1	0.1	Holding point 90mm, Bending 1 time. Bending 5mm	
Rapid change of temperature	2	0.3	-55°C (30min.) /+125°C (30min.) 1000 cycles	
Moisture resistance	2	0.1	40°C±2°C, 90~95%RH, 1000h 1.5h ON/0.5h OFF cycle	
Endurance at 70°C or rated terminal part temperature	2	0.2	$70^{\circ}C \pm 2^{\circ}C$ or rated terminal part temperature $\pm 2^{\circ}C$ 1000h 1.5h ON/0.5h OFF cycle	
High temperature exposure	1	0.1	+155°C, 1000h	

Precautions for Use

- The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON/OFF of load is repeated, especially when WU73 which have self-heating. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pa careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.
- In the resistance values of $50m\Omega$ or under, the resistance value after soldering may change depending on the size of pad pattern or solder amount. Make sure the effect of decline/increase of resistance value before designing.